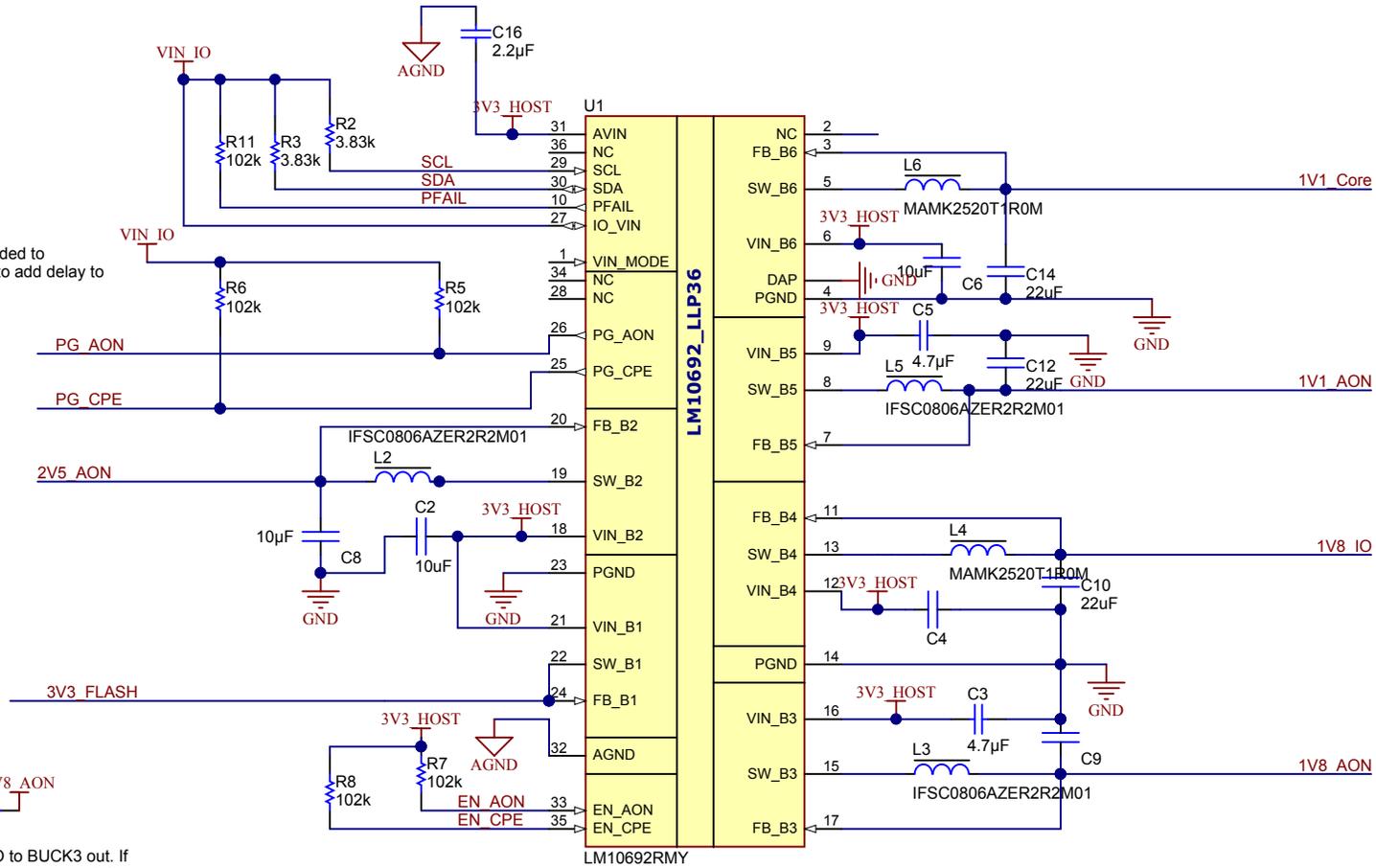


PFAIL signal controlled by AVIN level

PMP10842

Output capacitors shown represent capacitors directly at output of converters. More capacitance is required at the points of load.

Optional capacitors can be added to PG_CPE and PG_AON lines to add delay to those signals.



R12 connects the VIN_IO to BUCK3 out. If connection to another rail is desired, R12 can be un-mounted and a connection to VIN_IO soldered at this point.

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